

# RFM7N35, RFM7N40, RFP7N35, RFP7N40

7A, 350V and 400V, 0.75 Ohm,  
N-Channel Power MOSFETs

July 1998

## Features

- 7A, 350V and 400V
- $r_{DS(ON)} = 0.75\Omega$
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device
- Related Literature
  - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

## Ordering Information

PART NUMBER	PACKAGE	BRAND
RFM7N35	TO-204AA	RFM7N35
RFM7N40	TO-204AA	RFM7N40
RFP7N35	TO-220AB	RFP7N35
RFP7N40	TO-220AB	RFP7N40

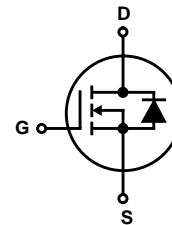
NOTE: When ordering, use the entire part number.

## Description

These are N-Channel enhancement mode silicon gate power field effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

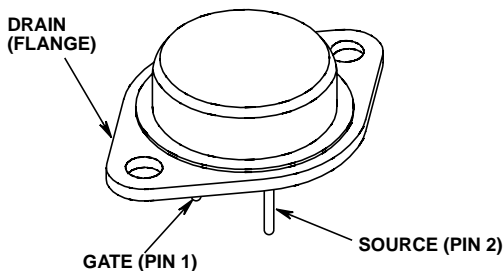
Formerly developmental type TA17424.

## Symbol

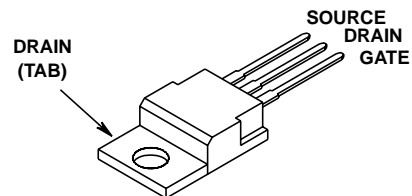


## Packaging

JEDEC TO-204AA



JEDEC TO-220AB



## RFM7N35, RFM7N40, RFP7N35, RFP7N40

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

	RFM7N35	RFM7N40	RFP7N35	RFP7N40	UNITS	
Drain to Source Voltage (Note 1) . . . . .	$V_{DSS}$	350	400	350	400	V
Drain to Gate Voltage ( $R_{GS} = 1\text{M}\Omega$ ) (Note 1) . . . . .	$V_{DGR}$	350	400	350	400	V
Continuous Drain Current . . . . .	$I_D$	7	7	7	7	A
Pulsed Drain Current (Note 3) . . . . .	$I_{DM}$	15	15	15	15	A
Gate to Source Voltage . . . . .	$V_{GS}$	$\pm 20$	$\pm 20$	$\pm 20$	$\pm 20$	V
Maximum Power Dissipation . . . . .	$P_D$	100	100	75	75	W
Linear Derating Factor (Above $25^\circ\text{C}$ ) . . . . .		0.8	0.8	0.6	0.6	$\text{W}/^\circ\text{C}$
Operating and Storage Temperature . . . . .	$T_J, T_{STG}$	-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$
Maximum Temperature for Soldering						
Leads at 0.063in (1.6mm) from Case for 10s . . . . .	$T_L$	300	300	300	300	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334 (for TO-220) . . . . .	$T_{pkg}$	260	260	260	260	$^\circ\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

**NOTE:**

- $T_J = 25^\circ\text{C}$  to  $125^\circ\text{C}$ .

### Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage RFM7N35, RFP7N35	$BV_{DSS}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	350	-	-	V
			RFM7N40, RFP7N40	400	-	-
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$ (Figure 8)	2	-	4	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = \text{Rated } BV_{DSS}, T_C = 25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}, T_C = 125^\circ\text{C}$	-	-	25	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	$\pm 100$	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = 7\text{A}, V_{GS} = 10\text{V}$ (Figures 6, 7)	-	-	0.75	$\Omega$
Drain to Source On Voltage (Note 2)	$V_{DS(ON)}$	$I_D = 7\text{A}, V_{GS} = 10\text{V}$	-	-	5.25	V
Turn-On Delay Time	$t_{d(ON)}$	$V_{DS} = 200\text{V}, I_D \approx 3.5\text{A}, R_G = 50\Omega,$ $R_L = 56\Omega, V_{GS} = 10\text{V}$ (Figures 10, 11, 12)	-	16	45	ns
Rise Time	$t_r$		-	54	75	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	170	250	ns
Fall Time	$t_f$		-	62	100	ns
Input Capacitance	$C_{ISS}$	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$ (Figure 9)	-	-	1600	pF
Output Capacitance	$C_{OSS}$		-	-	300	pF
Reverse-Transfer Capacitance	$C_{RSS}$		-	-	200	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$	RFM7N35, RFM7N40	-	-	1.25	$^\circ\text{C}/\text{W}$
		RFP7N35, RFP7N40	-	-	1.67	$^\circ\text{C}/\text{W}$

### Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage (Note 2)	$V_{SD}$	$I_{SD} = 7\text{A}$	-	-	1.4	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 7\text{A}, dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	870	-	ns

**NOTES:**

- Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
- Repetitive rating: pulse width limited by maximum junction temperature.

# RFM7N35, RFM7N40, RFP7N35, RFP7N40

## Typical Performance Curves Unless Otherwise Specified

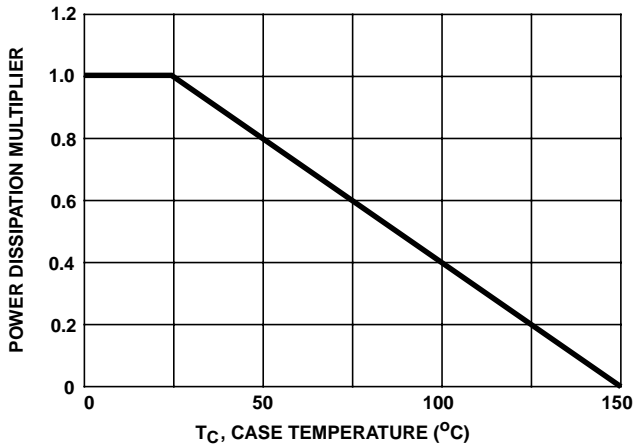


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

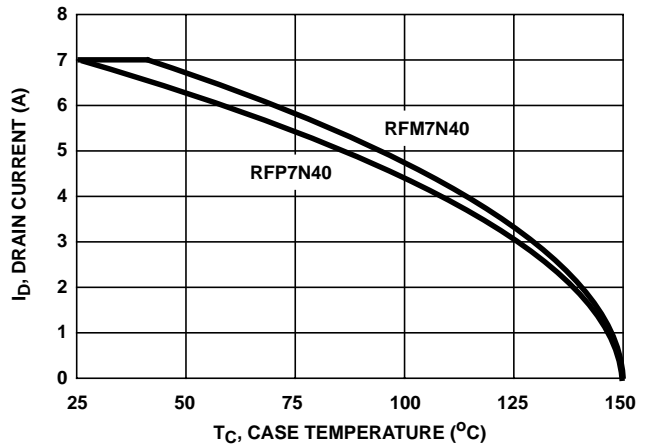


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

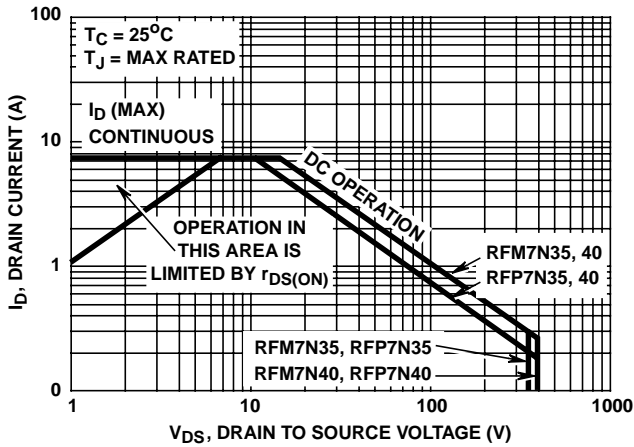


FIGURE 3. FORWARD BIAS SAFE OPERATING AREA

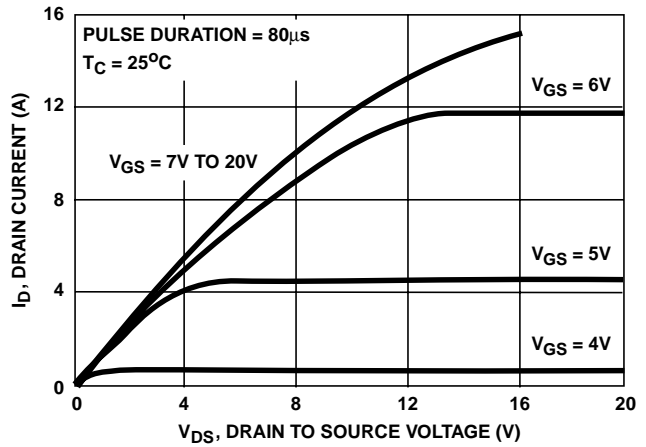


FIGURE 4. SATURATION CHARACTERISTICS

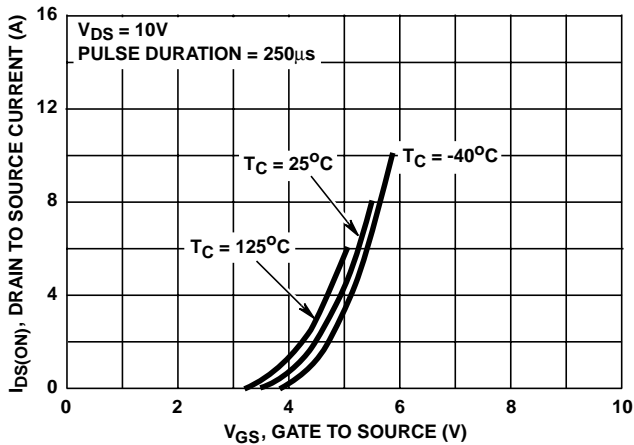


FIGURE 5. TRANSFER CHARACTERISTICS

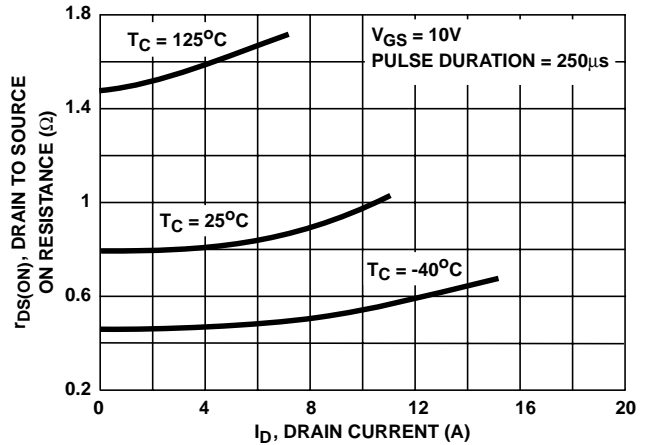


FIGURE 6. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

**Typical Performance Curves** Unless Otherwise Specified (Continued)

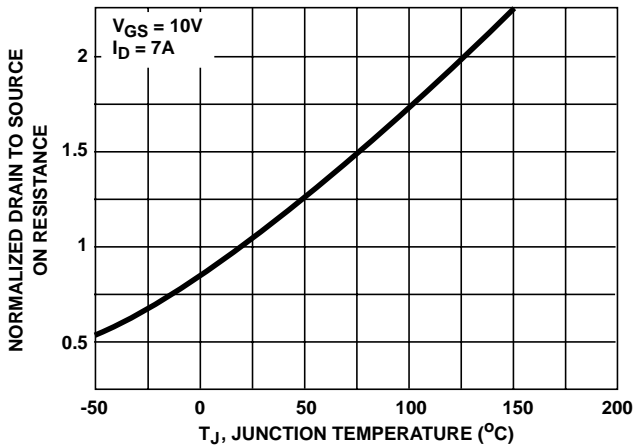


FIGURE 7. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

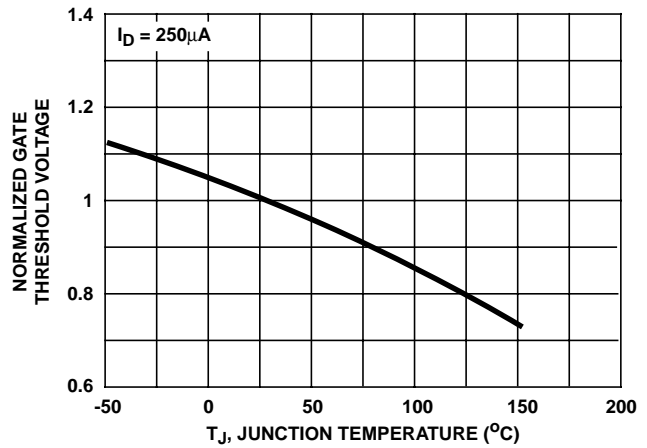


FIGURE 8. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

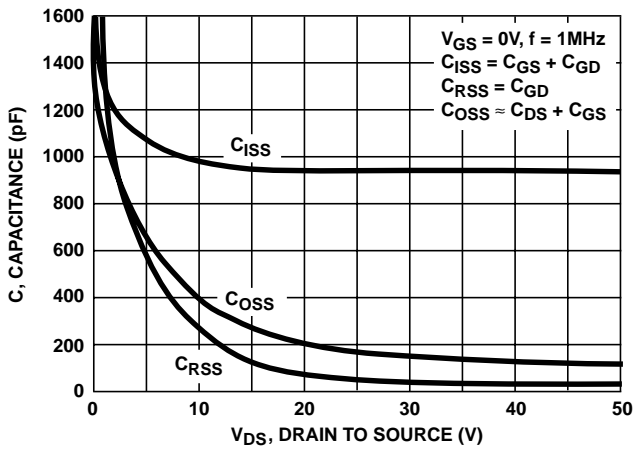
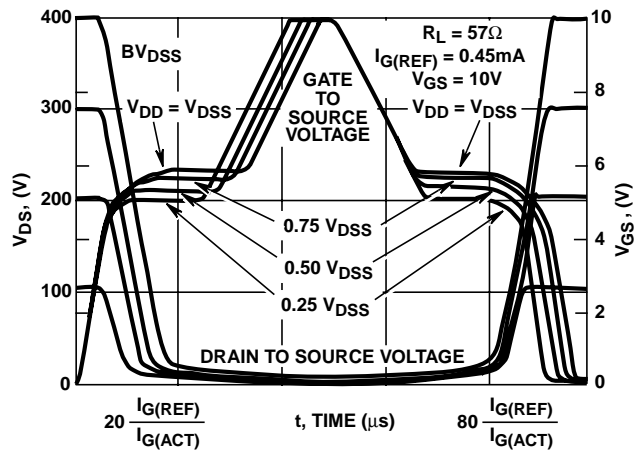


FIGURE 9. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Harris Application Notes AN7254 and AN7260.

FIGURE 10. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

**Test Circuits and Waveforms**

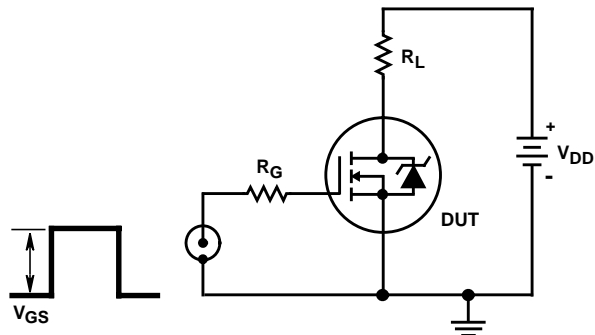


FIGURE 11. SWITCHING TIME TEST CIRCUIT

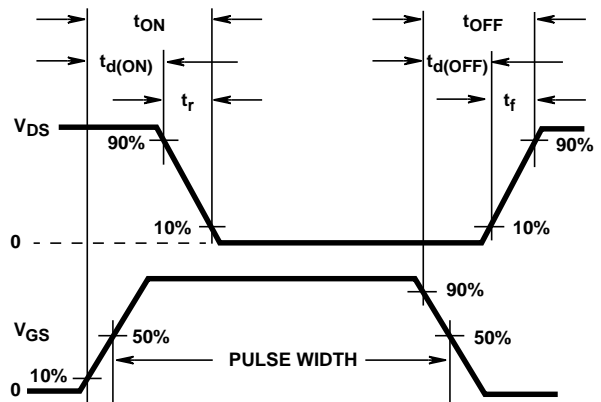


FIGURE 12. RESISTIVE SWITCHING WAVEFORMS